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ABSTRACT

This application report outlines the necessary and potential steps for replacing the Microchip KSZ8081MNX/RNB 10/100 Mb/s Ethernet PHY with TI's DP83826A.

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1 Purpose

While the KSZ8081MNX/RNB and the DP83826A have many similarities, several extra features are included in the DP83826A, improving performance and system optimization. This system rollover document outlines how to replace the KSZ8081MNX/RNB PHY microchip with TI's DP83826A by comparing differences including required external components, pin functions, feature set, and register operation. The impact to a design is dependent on the PHY configuration and features used.

2 Required Changes

This section describes the modifications required to transition from the KSZ8081MNX/RNB to the [DP83826A](#).

2.1 Strap Resistor Value

The DP83826A supports either basic Mode or enhanced mode. Basic mode supports the same bootstrap options as the KSZ8081. To set the DP83826A for basic mode, pin 1 (ModeSelect) must be tied to ground. In a KSZ8081 design, pin 1 is already tied to GND, so there is no change required to select the correct mode. To understand the difference between DP83826A basic Mode and enhanced mode, see the DP83826A data sheet.

Both devices use a 2-level strap that require a pull-up or pull-down resistor. The table below shows the difference in pull-up and pull-down resistor values between the DP83826A and the KSZ8081. See the TI Precision Labs Video '[How Do Ethernet bootstraps work?](#)' to properly calculate the correct strap resistors.

Table 2-1. Strap Resistor Values

	KSZ8081MNX/RNB	DP83826A
Pull-Up Resistor Value	4.7kΩ	2.49kΩ
Pull-Down Resistor Value	1kΩ	1.5kΩ

2.2 External Capacitor on Pin 2

The KSZ8081 requires two external decoupling capacitors on pin 2; 2.2uF and 0.1uF. The DP83826A only requires one external decoupling capacitor on pin 2 (CEXT) that is equal to 2nF.

Table 2-2. Value of External Capacitors on Pin 2

	KSZ8081MNX/RNB	DP83826A
External Capacitor Value	2.2μF and 0.1μF	2nF

2.3 Duplex Strap on Pin 16 (DP83826A Basic Mode)

- No change is needed on pin 16 whether KSZ8081 is being used in Half-Duplex or Full-Duplex mode, DP83826A is in the same mode as KSZ8081 for a given circuit.

Table 2-3. Full and Half Duplex Comparison

Pin Number	KSZ8081MNX/RNB	DP83826A Basic Mode
Pin 16	1: Half Duplex (Default) 0: Full Duplex	1: Half Duplex (Default) 0: Full Duplex

2.4 Selecting 10M with Auto-Negotiation Enabled (DP83826A Basic Mode)

KSZ8081MNX and DP83826A default to 100M speed. To select 10M speed, KSZ8081 recommends a pull-down on the strap along with a series resistor on the LED. For DP83826A Basic Mode, 10M speed selection is done through register configuration and the strap resistor on Pin 31 is removed.

- Remove the strap resistor on Pin 31 for 10M selection.
- Program register 0x0004 with 0x0061 to select 10M speed when auto-negotiation is enabled.
- Program register 0x0000 with 0x3300 to restart auto-negotiation.

2.5 Configuring LED_1 for Tx and Rx Activity for EtherCAT Slave (DP83826A Basic Mode)

The DP83826A and KSZ8081MN/RNB can use LED_1 to indicate Tx and Rx activity from a host ASIC or FPGA. Extended register configurations are required for DP83826A.

- Program register 0x0460 either with 0x0001 for the LED to stay high or with 0x0008 for a blinking LED
- Program register 0x0469 with 0x0004

2.6 Thermal Pad Adjustments in Layout

The DP83826A thermal pad is smaller than KSZ8081. [Table 2-4](#) lists the differences in package and DAP dimensions between the KSZ8081 and DP83826A. With the rollover between devices, there is still a sufficient gap between pins and DAP so that pins are not shorted.

Table 2-4. Package and DAP Dimension Differences

	KSZ8081	DP83826A
Package dimensions	5 × 5mm	5 × 5mm
Maximum DAP dimensions	3 × 3mm	2.2 × 2.2mm

The recommended design for best practices on the layout is to match the solder paste stencil with the DP83826A thermal pad. This means reducing the solder paste from 3 × 3mm to 2.1 × 2.1mm.

2.7 Physical Layer ID Register

The PHY Identifier Register 1 (PHYIDR1) and 2 (PHYIDR2) allows system software to determine the applicability of device specific software based on the vendor model number. The Identifiers Register 1 and Register 2 can be found in the DP83826A data sheet. The vendor model number is represented by bits 9 to 4 in PHYIDR2 (Address 0x3) listed in [Table 2-5](#).

Table 2-5. PHYID Comparison

Register Address	Register Name	Register Description	Device	
			DP83826A	KSZ8081MN/RNB
0x03	PHYIDR2	PHY ID 2	0xA116- BASIC 0xA136 - ENHANCED	0x1560- Rev A/A2 0x1561- Rev A3

3 Potential Changes

The following section describes the specific changes that can be required to be changed in converting to a DP83826A design. The default values for the DP83826A vs. KSZ8081MN/RNB can be enough for transition between parts.

3.1 MDIO Pull-Up Resistor on Pin 11

KSZ8081 requires an external pull-up resistor on the MDIO pin of the PHY. The DP83826A has an internal pull-up resistor of 10kΩ on this pin. An additional external pull-up resistor can be added if required.

3.2 MDIO Register Writes

The DP83826A and KSZ8081MN/RNB have both standard and extended SMI/MIIM (MDIO) registers.

DP83826A can access the standard registers through the indirect method (using standard registers 0x000D and 0x000E as outlined in IEEE 802.3). However, Microchip KSZ8081MN/RNB can only access the standard register set through the direct method (without using 0x000D and 0x000E registers).

KSZ8081MN/RNB also specifies the MMD address for all extended registers (for example 2 h) while DP83826A only uses MMD address 31 (0x001F) for all extended register writes and reads.

3.3 Capacitors on Center Tap of Magnetics

KSZ8081MN/RNB uses one 0.1uF capacitor on each center tap of magnetics. By contrast, DP83826A uses one 2nF capacitor on each center tap. TI recommends changing this capacitor value when replacing KSZ8081 with DP83826A.

4 Informational Changes

This section describes feature differences between the DP83826A and KSZ8081.

Table 4-1. DP83826A vs. KSZ8081MN/RNB Feature Set Comparison

Features	KSZ8081MN/RNB	DP83826A
VDDIO	1.8V, 2.5V, 3.3V	1.8V, 3.3V
NAND Tree Support	Supported	Not Supported
PHY Broadcast Address	Supported	Not Supported
MII Back-2-Back Mode	Supported	Supported in ENHANCED Mode for Repeater Functionality
Slow Oscillator Mode	Supported	Supported - known as Deep Power Down Mode

5 Pinout Mapping

5.1 Pin Mapping

The table below shows the pinout mapping between the DP83826A and KSZ8081MNX/RNB. For more details on the pin mapping as well as any updates made, see the [DP83826A data sheet](#).

Table 5-1. Pinout Mapping

Pin No.	KSZ8081MNX/RNB Pin Functions	DP83826A BASIC Mode Pin Functions	DP83826A ENHANCED Mode Pin Functions
1	GND	Mode Select	Mode Select
2	VDD_1.2	CEXT	CEXT
3	VDDA_3.3	VDDA3V3	VDDA3V3
4	RXM	RD_M	RD_M
5	RXP	RD_P	RD_P
6	TXM	TD_M	TD_M
7	TXP	TD_P	TD_P
8	XO	XO	XO
9	XI	XI/50MHzIn	XI/50MHzIn
10	REXT	RBIAS	RBIAS
11	MDIO	MDIO	MDIO
12	MDC	MDC	MDC
13	PHYAD0 (RXD3)	RX_D3	RX_D3
14	PHYAD1 (RXD2)	RX_D2	RX_D2
15	RXD1/ PHYAD2	RX_D1	RX_D1
16	RXD0/ DUPLEX	RX_D0	RX_D0
17	VDDIO	VDDIO	VDDIO
18	RXDV/ CONFIG2	RX_DV/CRS_DV	RX_DV/CRS_DV
19	RXC/ B-CAST_OFF	RX_CLK/50 MHz_Output	RX_CLK/50 MHz_RMII
20	RXER/ ISO	RX_ER	RX_ER
21	INTRP/ NAND_Tree#	INT	PWRDN/INT
22	TXC	TX_CLK	TX_CLK
23	TXEN	TX_EN	TX_EN
24	TXD0	TX_D0	TX_D0
25	TXD1	TX_D1	TX_D1
26	TXD2	TX_D2	TX_D2
27	TXD3	TX_D3	TX_D3
28	COL/ CONFIG0	COL	COL/LED2/GPIO
29	CRS/ CONFIG1	CRS	CRS/LED3
30	LED0/ NWAYEN_I	LED0	LED0
31	LED1/ SPEED	LED1	LED1
32	RST#	RST_N	RST_N

6 DP83826A Strap Configurations

6.1 Bootstrap Configurations

The following tables outline the DP83826A strap configurations in BASIC Mode. Unless stated otherwise in the previous subsections, the KSZ8081MN/RNB strap configurations are analogous. This table and more details about the bootstrap configurations can be found in the [DP83826A data sheet](#).

Table 6-1. PHY Address Strap Table

Pin Name	Strap Name	Pin Number.	Default	Mode	Function
RX_D3	Strap7	13	1		PHY_ADD0
				0	0
				1	1
RX_D2	Strap8	14	0		PHY_ADD1
				0	0
				1	1
RX_D1	Strap9	15	0		PHY_ADD2
				0	0
				1	1

Table 6-2. MAC Mode Selection Strap Table

Pin Name	Strap Name	Pin Number	Default	Strap 10	Strap 4	Function
COL	Strap4	28	0	0	0	MII MAC mode
				0	1	RMII leader mode
				1	1	RMII follower mode
CRS	Strap3	29	0	Reserved		
RX_DV	Strap10	18	0			

Table 6-3. Auto Negotiation Strap Table

Pin Name	Strap Name	Pin Number	Default	Mode	Function
LED0	Strap2	30	1	0	Auto Negotiation Disable
				1	Auto Negotiation Enable

Table 6-4. Speed Strap Table

Pin Name	Strap Name	Pin Number	Default	Mode	Function
LED1	Strap1	31	1	0	Speed 10M
				1	Speed 100M

Table 6-5. Full/Half Duplex Table

Pin Name	Strap Name	Pin Number	Default	Mode	Function
RX_D0	Strap0	16	1	0	Full Duplex
				1	Half Duplex

Table 6-6. MII Isolate Bootstraps

Pin Name	Strap Name	Pin Number	Default	Mode	Function
RX_ER	Strap6	20	0	0	MII Isolate Disable
				1	MII Isolate Enable

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